

CNW11AV-1

CNW11AV-2

CNW11AV-3

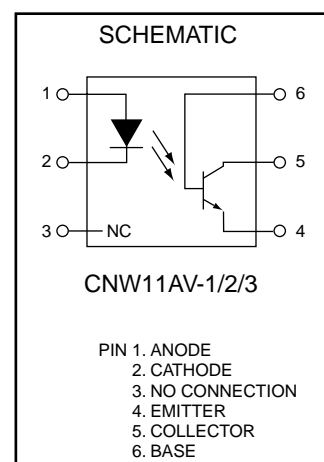
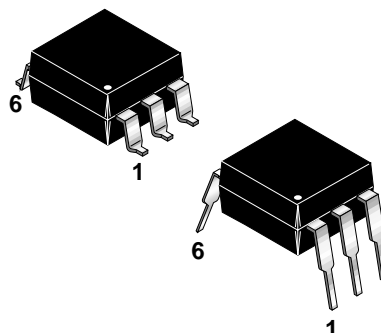
**DESCRIPTION**

The CNW11AV series are high voltage optocouplers in a wide body dual-in-line package (DIP).

Each optocoupler consists of a GaAs infrared emitter optically coupled to a silicon npn phototransistor with the base connected.

**FEATURES**

- Minimum 2 mm isolation thickness between emitter and receiver
  - A wide body encapsulation with a pin distance of 10.16 mm
  - An external clearance of 9.6 mm minimum and an external creepage of 10 mm minimum
  - High current transfer ratio and low saturation voltage, making the device suitable for use with TTL integrated circuits
  - High degree of AC and DC insulation (4000 V (RMS) and 5656 V (DC))
  - Collector-emitter breakdown Voltage: 70 V
  - Low isolation capacitance of 0.5 pF maximum
  - UL recognized (File # E90700)
  - VDE recognized (File # 76876)
- Ordering option '300' (e.g. CNW11AV-1.300)



**ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Value	Units
<b>TOTAL DEVICE</b>			
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C
Ambient Operating Temperature Range	T <sub>OPR</sub>	-40 to 100	°C
Lead Soldering Temperature	T <sub>SOL</sub>	260 for 10 sec	°C
Junction Temperature	T <sub>J</sub>	125	°C
<b>EMITTER</b>			
Forward Current - Continuous	I <sub>F</sub>	100	mA
Forward Current - Peak (t <sub>on</sub> = 10µs, δ = 0.01)	I <sub>F(pk)</sub>	3	A
Reverse Voltage	V <sub>R</sub>	6	V
Total Power Dissipation @ T <sub>A</sub> = 25°C Derate Linearly From 25°C	P <sub>D</sub>	200	mW
		2.0	mW/°C
<b>DETECTOR</b>			
Collector Current-Continuous	I <sub>C</sub>	100	mA
Emitter-Collector Voltage	V <sub>ECO</sub>	7	V
Collector-Emitter Voltage	V <sub>CEO</sub>	70	V
Collector-Base Voltage	V <sub>CBO</sub>	70	V
Total Power Dissipation @ T <sub>A</sub> = 25°C Derate Linearly From 25°C	P <sub>D</sub>	200	mW
		2.0	mW/°C

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**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  Unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit			
<b>EMITTER</b> Input Forward Voltage	$I_F = 10 \text{ mA}$	$V_F$	0.8	1.15	1.50	V			
	$I_F = 10 \text{ mA}, T_A = -55^\circ\text{C}$		0.9	—	1.70				
	$I_F = 10 \text{ mA}, T_A = 100^\circ\text{C}$		0.7	—	1.40				
Reverse Leakage Current	$V_R = 6.0 \text{ V}$	$I_R$	—	—	10	$\mu\text{A}$			
Input Capacitance	$V_I = 0, f = 1 \text{ MHz}$	$C_J$	—	25	100	pF			
<b>DETECTOR</b> Collector-Emitter Breakdown Voltage	$I_C = 1.0 \text{ mA}$	$BV_{CEO}$	70	—	—	V			
			Collector-Base Breakdown Voltage	$I_C = 0.1 \text{ mA}$	$BV_{CBO}$	70	—	—	V
			Emitter-Collector Breakdown Voltage	$I_E = 0.1 \text{ mA}$	$BV_{ECO}$	7	—	—	V
			Emitter-Base Breakdown Voltage	$I_E = 0.1 \text{ mA}$	$BV_{EBO}$	7	—	—	V
			Collector-Emitter Dark Current	$V_{CE} = 10 \text{ V}, I_F = 0, T_A = 25^\circ\text{C}$	$I_{CEO}$	—	0.5	50	nA
						$V_{CE} = 10 \text{ V}, I_F = 0, T_A = 70^\circ\text{C}$	—	—	10
			Collector-Base Cut-off Current	$I_F = 0, V_{CB} = 10 \text{ V}$	$I_{CBO}$	—	—	20	nA

**ISOLATION CHARACTERISTICS**

Characteristic	Test Conditions	Symbol	Min	Typ	Max	Units
Input-Output Isolation Voltage	DC Value, Time = 1 min.	$V_{ISO}$	5,656			V
	RMS Value, Time = 1 min.		4,000			
Isolation Resistance	$V_{I-O} = \pm 500 \text{ VDC}$	$R_{ISO}$	1	10		$T\Omega$
Isolation Capacitance	$V = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{ISO}$		0.3	0.5	pF
Output Capacitance	$V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$	$C_O$		4.5		pF

**TRANSFER CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  Unless otherwise specified.)

DC Characteristics	Test Conditions	Symbol	Device	Min	Typ	Max	Units
Output/Input Current Transfer Ratio	$I_F = 10 \text{ mA}, V_{CE} = 10 \text{ V}$	CTR	CNW11AV-1	100		300	%
			CNW11AV-2	50			
			CNW11AV-3	20			
Collector-Emitter Saturation Voltage	$I_F = 20 \text{ mA}, I_C = 2 \text{ mA}$	$V_{CE(SAT)}$	All		0.1	0.4	V
Common Mode Rejection Ratio	$I_C = 2 \text{ mA}, V_{CC} = 5 \text{ V}, f = 10 \text{ kHz}, R = 1 \text{ k}\Omega$	CMRR	All		-60		dB
AC Characteristics	Test Conditions	Symbol	Device	Min	Typ	Max	Units
<b>Saturated Switching Times</b>							
Turn-On Time (fig. 2 & 3)	$I_C = 2 \text{ mA}, V_{CC} = 10 \text{ V}, R_L = 100 \Omega$	$t_{on}$	All		3	15	$\mu\text{s}$
Turn-Off Time (fig. 2 & 3)		$t_{off}$	All		2.5	15	$\mu\text{s}$

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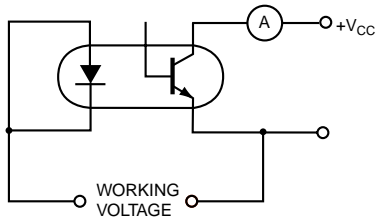


Fig. 1 Test Circuit

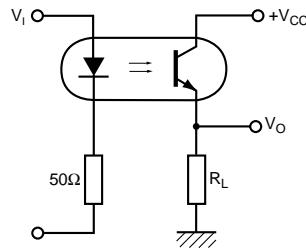


Fig. 2 Switching Circuit

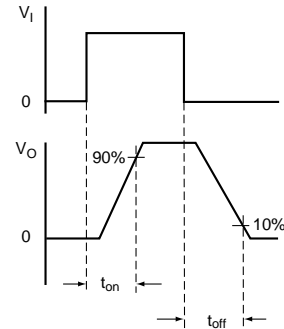


Fig. 3 Waveforms

Fig. 4 LED Forward Voltage vs. Forward Current

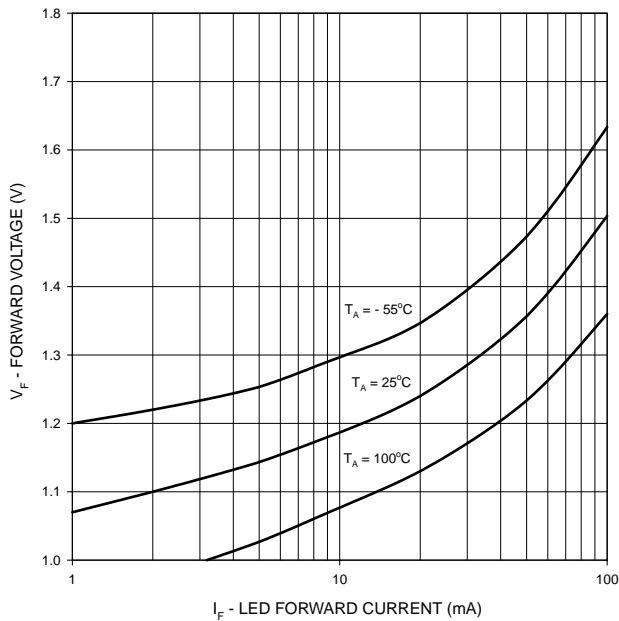


Fig. 5 Normalized CTR vs. Forward Current

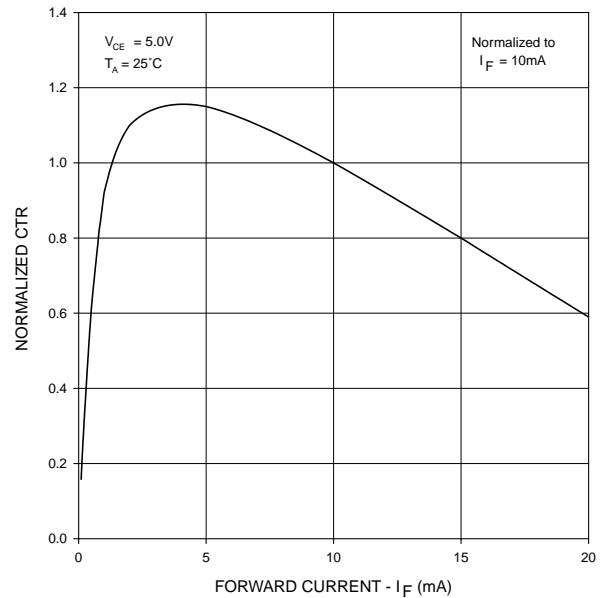


Fig. 6 Normalized CTR vs. Temperature

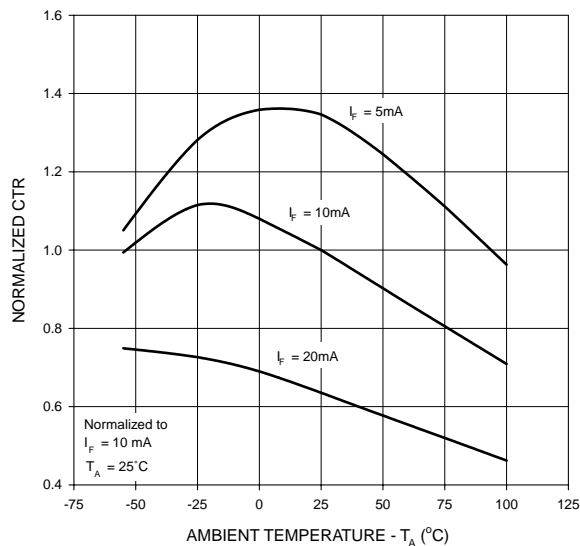
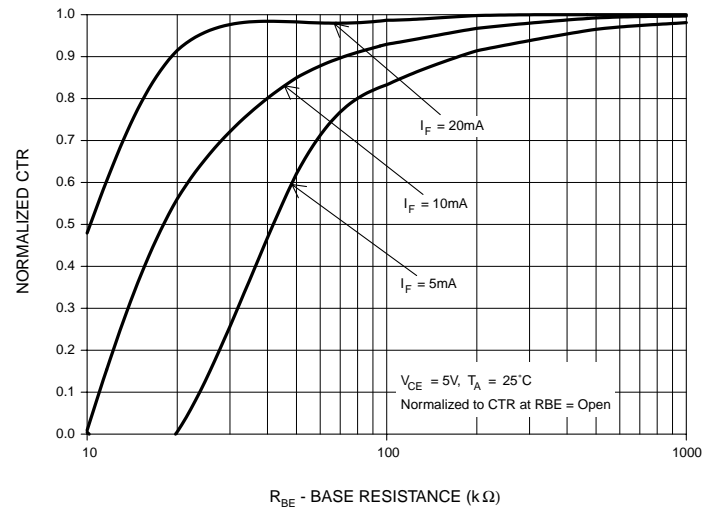


Fig. 7 CTR vs. R<sub>BE</sub> (Unsaturated)

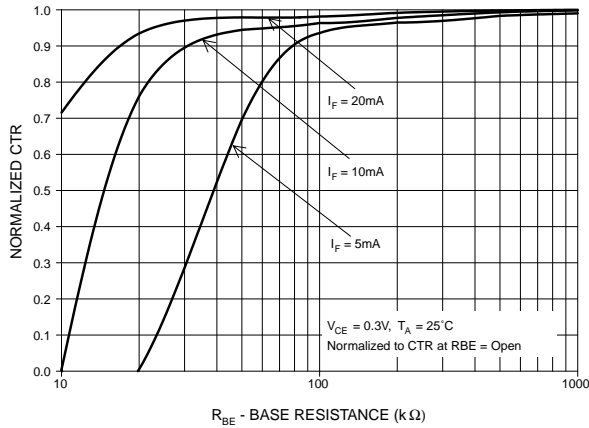


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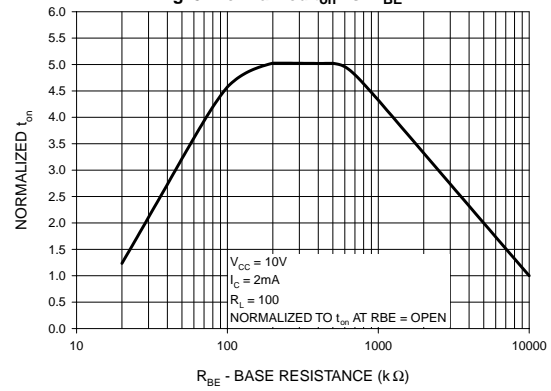
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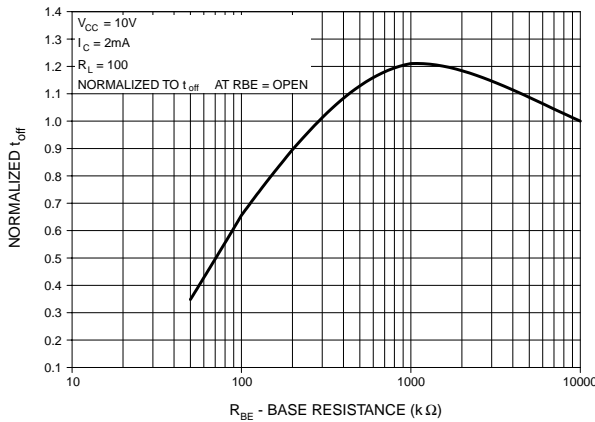
**Fig. 8 CTR vs. R<sub>BE</sub> (Saturated)**



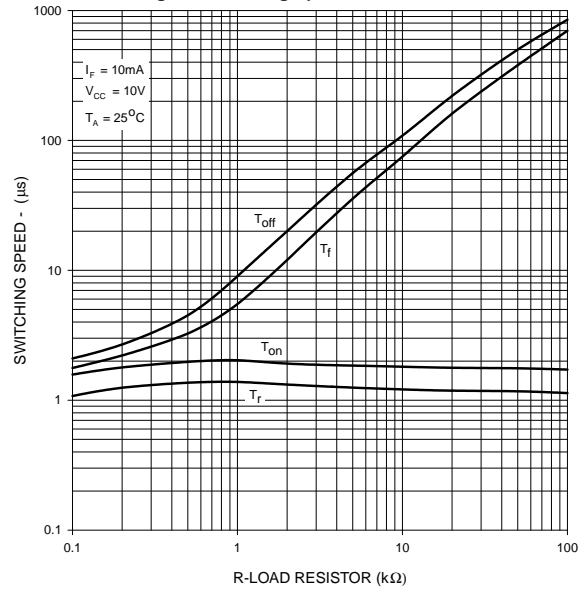
**Fig. 9 Normalized t<sub>on</sub> vs. R<sub>BE</sub>**



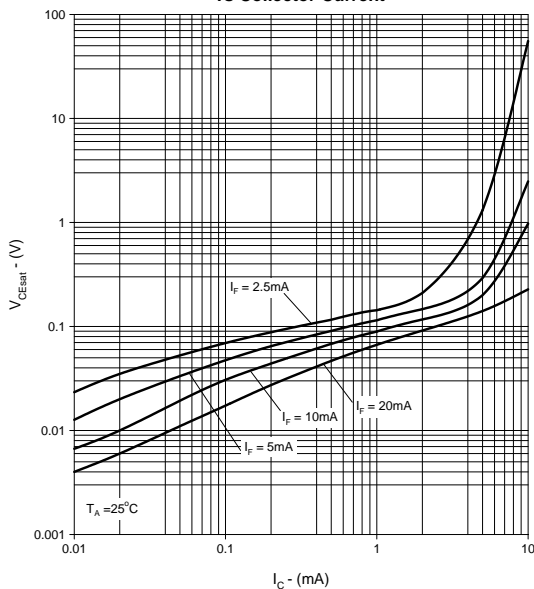
**Fig. 10 Normalized t<sub>off</sub> vs. R<sub>BE</sub>**



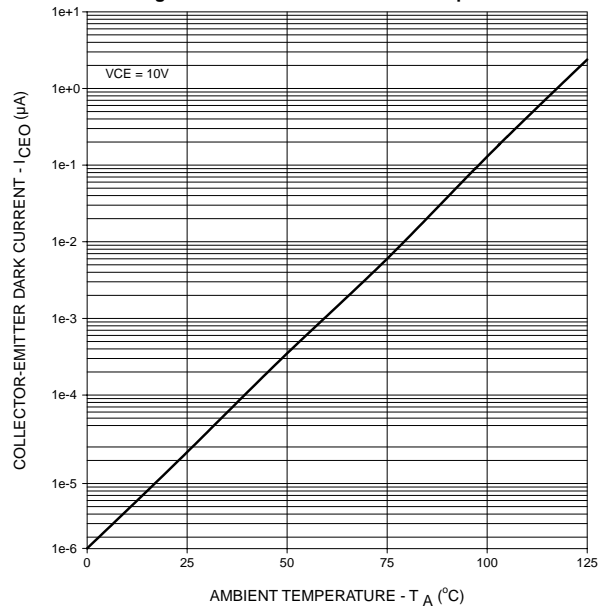
**Fig. 11 Switching Speed vs. Load Resistor**



**Fig. 12 Collector-Emitter Saturation Voltage vs Collector Current**



**Fig. 13 Dark Current vs. Ambient Temperature**

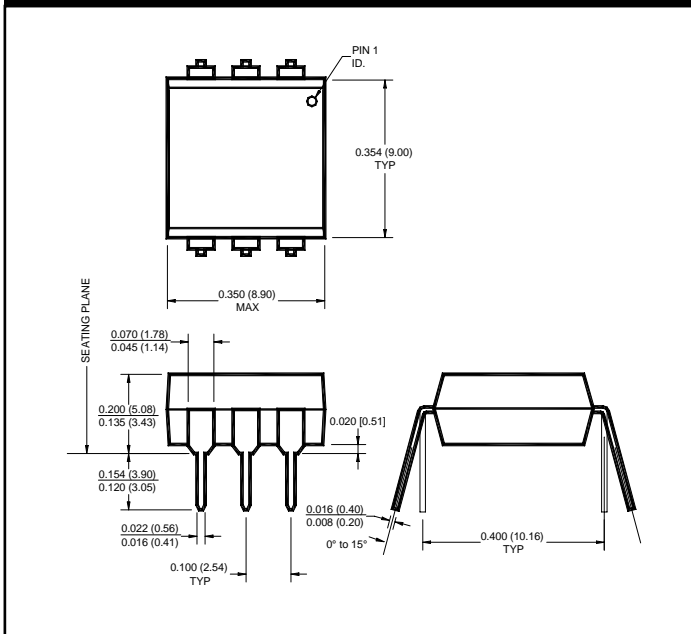


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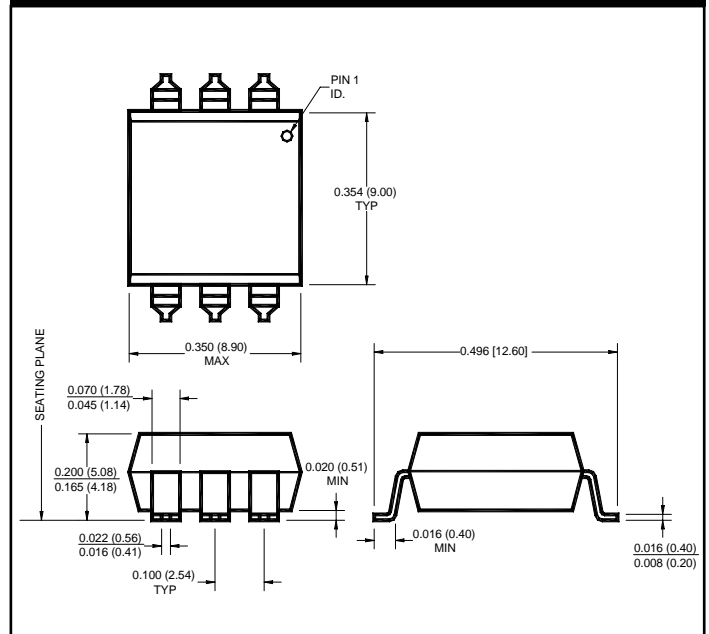
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**Package Dimensions (Through Hole)**



**Package Dimensions (Surface Mount)**



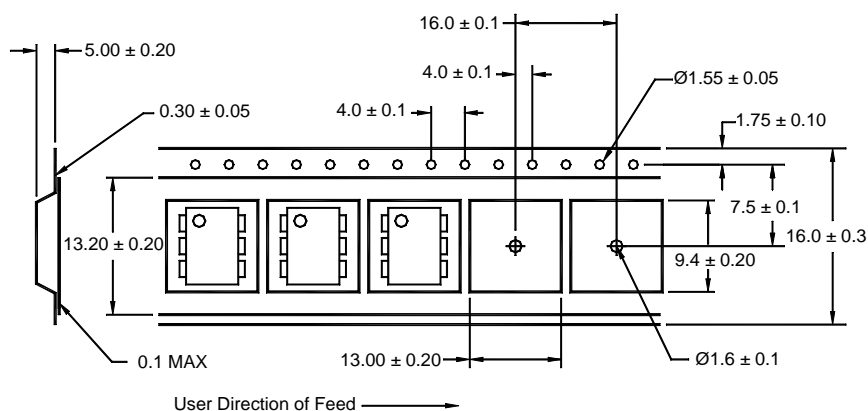
**NOTE**

All dimensions are in inches (millimeters)

**ORDERING INFORMATION**

Option	Order Entry Identifier	Description
S	.S	Surface Mount Lead Bend
SD	.SD	Surface Mount; Tape and reel
300	.300	VDE 0884

**Carrier Tape Specifications ("D" Taping Orientation)**



**NOTE**

All dimensions are in inches (millimeters)

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